microATX Chassis Checklist

Version 1.1

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REVISION HISTORY

Changes from Version 1.0 to Version 1.1

Introduction – updated the Web site URL.

Section 5 – Increase in the maximum component height restriction. Zones C, D, and E formerly specified three different height restrictions. This revision replaces those three zones (C, D, and E) with one maximum component height restriction zone (C) for the entire region. Figure 3 has been updated to reflect this change.

Sections 7 and 8 – Removed former Section 7 (PC 98 Recommendations) and renumbered the two sections that followed.

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Version 1.1, June 2002

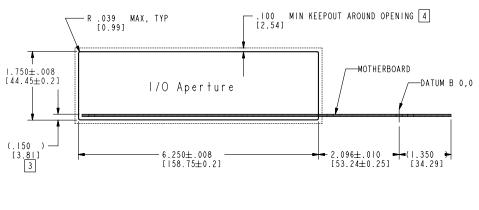
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microATX Chassis Checklist Version 1.1

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mici	<u> </u>	eference for determining compliance to the to be a comprehensive process but rather to spot
	erences are from revision 1.1 of the <i>micro</i> st version of the specification, see the Wel	ATX Motherboard Interface Specification. For the site: http://www.formfactors.org
1	Chassis Features De	escription
The	checklist features are divided in three cate	egories:
(R)	= Required feature	
(O)	= Optional feature	
(I)	= Informational feature	
2	General Chassis Info	ormation
(I)	Overall height of unit (includes feet)	
(I)	Overall width of unit	
(I)	Overall depth of unit	
(I)	Number of 3.5" drive bays	
(I)	Number of 5.25" drive bays	
(I)	Number of total add-in slots	

3 I/O Shield Aperture Features

See Figure 1.				
(R)	I/O Aperture Width	6.250±0.008"	Yes	No Actual
		[158.75±0.2 mm]		
(R)	I/O Aperture Height	1.750±0.008"	Yes	No Actual
		[44.45±0.2 mm]		
(R)	I/O Aperture Keepout Area	0.100" Min.	Yes	No Actual
		[2.54 mm]		
(R)	I/O Aperture Corner Radius	0.039" Max. Typ.	Yes	No Actual
		[0.99 mm]		
(R)	Motherboard Standoffs to I/O Aperture	0.086±0.010"	Yes	No Actual
		[2.18±0.25 mm]		
(R)	Relationship to Datum B - Width	2.096±0.010"	Yes	No Actual
		[53.24±0.25 mm]		
(R)	Relationship to Datum B - Depth	0.483±0.010"	Yes	No Actual
		[12.27±0.25 mm]		
(R)	Sheetmetal Thickness at I/O Aperture	0.037" to 0.052"	Yes \square	No Actual
	_	[0.94 mm to 1.32 r	nml	



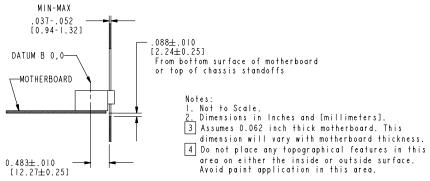


Figure 1: I/O Aperture Measurements

4 Motherboard Mounting Features

See Figure 2. (R) Features for mounting microATX motherboard (see Figure 2) No Yes (I) Features for mounting ATX motherboard (see Figure 2) Yes No Features for mounting miniATX motherboard (see ATX spec.) (I) Yes No No obstructions to mounting microATX motherboard (R) Yes No Mounting hole "S" is implemented with a removable standoff (R) Yes No Add-in card slots align with microATX motherboard (R) Yes \square No \square (I) Notes, mounting features:

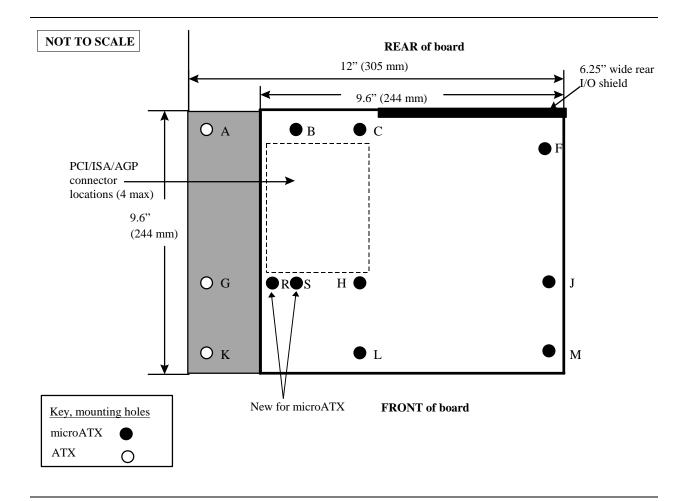
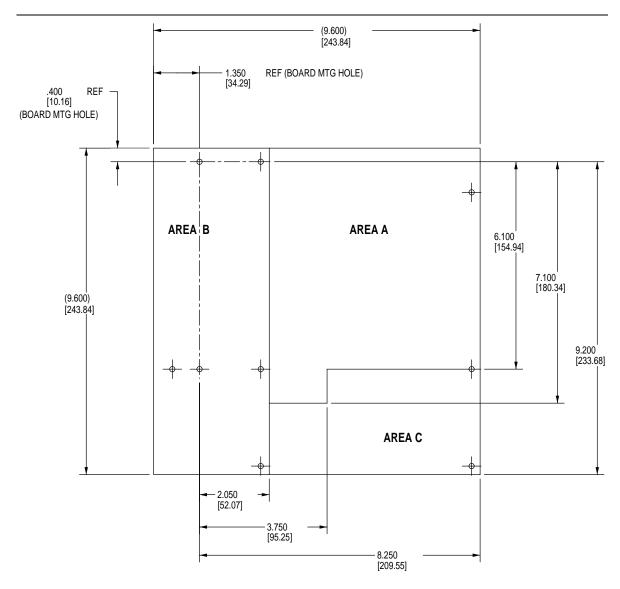


Figure 2: Motherboard Mounting Features

5 Motherboard Component Height Restrictions

See 1	Figure 3.		
	ary board side. These are component heightsion (i.e., vibration and shock during shipp		ve room for dynamic
(R)	Maximum component height in Zone "A"	2.80 inches [71.12mm]	Yes No No
(R)	Required chassis clearance in Zone "A"	3.00 inches [76.20mm]	Yes No No
(O)	recommended:	3.50 inches [88.90mm]	Yes No No
(R)	Maximum component height in Zone "B"	0.60 inches [15.24mm]	Yes No No
(R)	Maximum component height in Zone "C"	1.50 inches [38.10mm]	Yes No



Area	Maximum component height (in inches)	
A	Motherboard component height, 2.80 inches [71.12mm] maximum	
	Chassis clearance over motherboard, 3.0 inches [76.20mm] required	
	Chassis clearance over motherboard, 3.5 inches [88.90mm] recommended	
В	0.60 inches [15.24mm] (expansion slot area)	
С	1.50 inches [38.10mm] (see Note)	

Note: These component heights assume a PCB thickness of 0.062" [1.575mm].

Figure 3: Height Restriction Areas

6 Power Supply Mounting Features

See Figure 4 and Figure 5.			
(I)	Chassis accepts ATX-style power supply	Yes No No	
(I)	ATX: Features for internal mounting tab	Yes No No	
(I)	ATX: Location of 4 external mounting holes (see Figure 4)	Yes No	
(I)	ATX: Adequate opening for rear vent and AC plug	Yes No	
(I)	Chassis accepts SFX-style power supply	Yes No	
(I)	SFX: Features for internal mounting tab	Yes No	
(I)	SFX: Location of 3 external mounting holes (see Figure 5)	Yes No	
(I)	SFX: Adequate opening for rear vent and AC plug	Yes No	
(I)	Notes, power supply:		

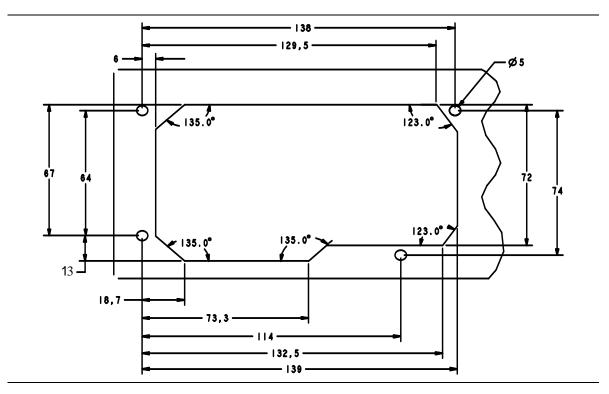


Figure 4: ATX Power Supply Mounting Holes

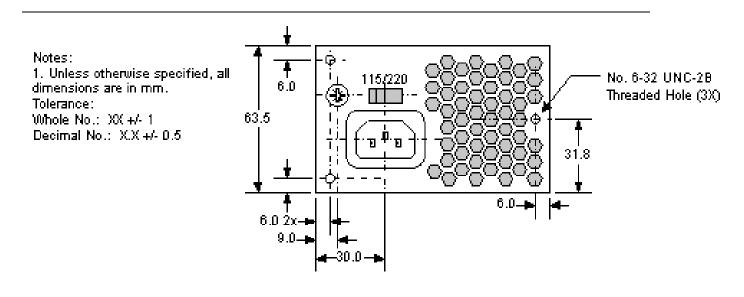


Figure 5: SFX Power Supply Mounting Holes

7	Thermal Features	
(I)	Provision for optional secondary fan	Yes No No
(I)	Adequate venting in the front of chassis	Yes No No
(I)	Adequate venting in the rear of chassis	Yes No No
(I)	Notes, thermal features:	
0	EMI Conciderations	
8	EMI Considerations	
(I)	I/O shield provides contact between I/O ports and chassis	Yes No
(I)	Open external drive bays contain EMI shields	Yes No No
(I)	Filler panels of empty add-in card slots seated	Yes No No
(I)	Chassis seams have features to enhance grounding	Yes No No
(I)	Motherboard mounting features provide grounding	Yes No No

(I)

Notes, EMI features: